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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/796,514	03/09/2004	John P. Snyder	6932.14467.05	1961
40064 7590 07/24/2008 LEMAIRE PATENT LAW FIRM, P.L.L.C. P.O. BOX 1818 PURNISYM LE, MN 55227			EXAMINER	
			KIM, SU C	
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		2823		
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			07/24/2008	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)		
	10/796,514	SNYDER ET AL.		
Office Action Summary	Examiner	Art Unit		
	SU C. KIM	2823		
The MAILING DATE of this communication ap Period for Reply	opears on the cover sheet with the	correspondence address		
A SHORTENED STATUTORY PERIOD FOR REPOWHICHEVER IS LONGER, FROM THE MAILING IT Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication. If NO period for reply is specified above, the maximum statutory period. Failure to reply within the set or extended period for reply will, by statu Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	DATE OF THIS COMMUNICATIO .136(a). In no event, however, may a reply be tid d will apply and will expire SIX (6) MONTHS fron the, cause the application to become ABANDONI	N. mely filed n the mailing date of this communication. ED (35 U.S.C. § 133).		
Status				
1) ☐ Responsive to communication(s) filed on 11. 2a) ☐ This action is FINAL . 2b) ☐ Th 3) ☐ Since this application is in condition for allowed closed in accordance with the practice under	is action is non-final. ance except for formal matters, pr			
Disposition of Claims				
4) Claim(s) 1-8,10-21,23-31 and 33-65 is/are per 4a) Of the above claim(s) is/are withdress. 5) Claim(s) is/are allowed. 6) Claim(s) 1-8,10-21,23-31 and 33-65 is/are resolved. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/	awn from consideration.			
9) The specification is objected to by the Examir	oor			
10) ☐ The drawing(s) filed on <u>09 March 2004</u> is/are: Applicant may not request that any objection to the Replacement drawing sheet(s) including the corre	a)⊠ accepted or b)⊡ objected in abeyance. Se ction is required if the drawing(s) is ob	ee 37 CFR 1.85(a). ojected to. See 37 CFR 1.121(d).		
Priority under 35 U.S.C. § 119				
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 				
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal I 6) Other:	oate		

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DETAILED ACTION

Response to Arguments

1. Applicant's arguments, see applicant argument (pages 16-19), filed on 4/11/2008, with respect to the rejection(s) of claim(s) 1-8, 10-21, 23-31, & 33-65 under 35 U.S.C 102(e) have been fully considered and are persuasive. Therefore, the rejection has been withdrawn. However, upon further consideration, a new ground(s) of rejection is made in view of Gardner et al. (US 6,207,995).

Claim Rejections - 35 USC § 112

2. The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

The term "thin" in claims 33, 34, 44, 45, 55, & 56 are a relative term which renders the claim indefinite. The term "thin" is not defined by the claim, the specification does not provide a standard for ascertaining the requisite degree, and one of ordinary skill in the art would not be reasonably apprised of the scope of the invention.

Claim Rejections - 35 USC § 102

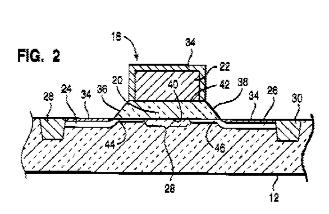
3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

4. Claims 1-4, 6-8, 10, 12, 14-18, 20-21, 23-27, 29-31, 34, 44, & 55 are rejected under 35 U.S.C. 102(b) as being anticipated by Gardner et al. (US 6,207,995).

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Regarding claims 1, 15, & 24, Gardner discloses that a method of manufacture of a device for regulating the flow of electrical current, the method comprising:

providing for a semiconductor substrate 12 (Fig. 2);

providing for an electrically insulating layer 38 in contact with the semiconductor substrate 12 (Fig. 2), the insulating layer having a dielectric constant greater than 4.0,7.6, or 15 (col. 5, lines 15-25, note: a dielectric constant of TiO2 is approximately 50-60);

providing for a gate electrode 20 in contact with at least a portion of the insulating layer 38 (Fig. 2); and

providing a source electrode and a drain electrode 34 in contact with the semiconductor substrate 12 and proximal to the gate electrode 22 wherein a channel 28 is formed between the source electrode and the drain electrode 34, and further wherein at least one of the source electrode and the drain electrode forms a Schottky contact

(note: silicide) or Schottky-like region with the semiconductor substrate and channel (Fig. 2).

Regarding claims 2-3, 16-17, & 25-26, as applied to claims 1, 15, & 24, Gardner discloses that the source and drain electrode are formed from a member of the group consisting of: platinum silicide, palladium silicide and iridium silicide (Col. 8, lines 11-19).

Regarding claims 4, 18, & 27, as applied to claims 1, 15, & 24, Gardner discloses that the insulating layer is formed from a member of the group consisting of metal oxide (Col. 5, lines 15-25).

Regarding claims 6, 20, & 29, as applied to claims 1, 15, & 24, Gardner discloses that the Schottky contact or Schottky-like region is formed at least in areas adjacent to the channel (Fig. 2).

Regarding claims 7, 21, & 30, as applied to claims 1, 15, & 24, Gardner discloses that an entire interface between at least one of the source electrode and drain electrode and the semiconductor substrate forms a Schottky contact 34 or Schottky-like region with the semiconductor substrate (Fig. 2).

Regarding claims 8, 23, & 31, as applied to claims 1, 15, & 24, Gardner discloses that dopants are introduce into the channel (col. 1, lines 14-15, note: substrate is lightly doped).

Regarding claim 10, as applied to claims 2 or 3, Gardner discloses that the insulating layer is formed from a member of the group consisting of metal oxide (Col. 5, lines 15-25).

Regarding claim 12, as applied to claims 2 or 3, Gardner discloses that the Schottky contact or Schottky-like region is formed at least in areas adjacent to the channel (Fig. 2).

Regarding claim 14, as applied to claims 2 or 3, Gardner discloses that providing a source electrode and a drain electrode 34 in contact with the semiconductor substrate 12 is performed at a processing temperature of less that about 800 °C (col. 8, lines 12-18).

Regarding claims 33, 44, & 55, Gardner discloses a method for manufacture of a device for regulating the flow of electrical current, the method comprising:

providing for a semiconductor substrate 12 (Fig. 2);

providing for an electrically insulating layer 38 in contact with the semiconductor substrate 12 (Fig. 2), the insulating layer having a dielectric constant greater than 4.0,7.6, or 15 (col. 5, lines 15-25, note: a dielectric constant of TiO2 is approximately 50-60);

providing for a gate electrode 20 in contact with at least a portion of the insulating layer 38 (Fig. 2);

exposing the semiconductor substrate on one or more areas proximal to the gate electrode;

providing for a thin film of metal on at least a portion of the exposed semiconductor substrate; and

reacting the metal with the exposed semiconductor substrate such that a source electrode and a drain electrode 34 formed and wherein a channel 28 is formed between

the source electrode and the drain electrode 34, and further wherein at least one of the source electrode and the drain electrode forms a Schottky contact (note: silicide) or Schottky-like region with the semiconductor substrate and channel (Fig. 2, col 8, lines 4-40).

Claim Rejections - 35 USC § 103

- 5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 6. Claims 34-39, 41-43, 45-50, 52-54, 56-61, & 63-65 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gardner et al. (US 6,207,995) in view of Su et al. (US 5,208,472).

Regarding claims 34, 45, & 56, as applied to claims 33, 44, & 55, Gardner discloses that depositing a thin conductive film 50 on the insulating layer 48 (Fig. 3); pattering and etching the conductive film to form a gate electrode 22 (Fig. 4 & 5).

Gardner fails to teach forming one or more thin insulating layers on one or more sidewalls of the gate electrode.

However, Hossain discloses forming one or more thin insulating layers on one or more sidewalls 19 & 22 of the gate electrode 16 (Fig. 6).

Therefore, it would have been obvious to one of ordinary skill in the art at the time of applicant(s) claimed invention was made to provide Gardner with forming one or more thin insulating layers on one or more sidewalls of the gate electrode as taught by

Su in order to reduce shorting between the gate and the source/drain region and decreases the damage induced by the stress of the silicide film (Col. 3, lines 6-8).

Regarding claims 35, 46, & 57, as applied to claims 33, 44, & 55, Gardner and Su in combinations disclose that removing metal not reacted during the reacting process (Gardner, col. 8, lines 26-30).

Regarding claims 36, 47, & 58, as applied to claims 33, 44, & 55, Gardner and Su in combinations disclose that the reacting comprising thermal annealing (Gardner, col. 8, lines 13-40).

Regarding claims 33-38, 48-49, & 59-60, as applied to claims 33, 44, & 55, Gardner and Su in combinations disclose that the source and drain electrode are formed from a member of the group consisting of: platinum silicide, palladium silicide and iridium silicide (Gardner, col. 8, lines 11-19).

Regarding claims 39, 50, & 61, as applied to claims 33, 44, & 55, Gardner and Su in combinations disclose that the insulating layer is formed from a member of the group consisting of metal oxide (Gardner, col. 5, lines 15-25).

Regarding claims 41, 52, & 63, as applied to claims 33, 44, & 55, Gardner and Su in combinations disclose that the Schottky contact or Schottky-like region is formed at least in areas adjacent to the channel (Gardner, Fig. 2).

Regarding claims 42, 53, & 64, as applied to claims 33, 44, & 55, Gardner and Su in combinations disclose that an entire interface between at least one of the source electrode and drain electrode and the semiconductor substrate forms a Schottky contact 34 or Schottky-like region with the semiconductor substrate (Gardner, Fig. 2).

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Regarding claims 43, 54, & 65, as applied to claims 33, 44, & 55, Gardner and Su in combinations disclose that dopants are introduce into the channel (Gardner, col. 1, lines 14-15, note: substrate is lightly doped).

7. Claims 5, 11, 13, 19, & 28 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gardner et al. (US 6,207,995) in view of Buchanan et al. (US 6,245,616).

Regarding claim 5, 11, 19, 28, as applied to claims 5, 2 or 3, 15, & 24, Gardner discloses the insulating layer 20.

Gardner fails to teach the insulating layer is formed from an oxy-nitride stack.

However, Buchanan suggests that the insulating layer is formed from an oxynitride stack 20 (Fig. 1).

Therefore, it would have been obvious to one of ordinary skill in the art at the time of applicant(s) claimed invention was made to provide Gardner with the insulating layer is formed from an oxy-nitride stack as taught by Buchanan in order to reduce channel hot electron damage (col. 1, lines 14-15).

Regarding claim 13, as applied to claim 11, Gardner and Buchanan in combinations disclose that the Schottky contact or Schottky-like region is formed at least in areas adjacent to the channel (Gardner, Fig. 2).

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8. Claims 40, 51, & 62 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gardner et al. (US 6,207,995) in view of Su et al. (US 5,208,472) and further in view of Buchanan et al. (US 6,245,616).

Regarding claim 40, 51, & 62, as applied to claims 33, 44, & 55, Gardner and Su in combinations disclose the insulating layer 20.

Gardner and Su fail to teach the insulating layer is formed from an oxy-nitride stack.

However, Buchanan suggests that the insulating layer is formed from an oxynitride stack 20 (Fig. 1).

Therefore, it would have been obvious to one of ordinary skill in the art at the time of applicant(s) claimed invention was made to provide Gardner and Su with the insulating layer is formed from an oxy-nitride stack as taught by Buchanan in order to reduce channel hot electron damage (col. 1, lines 14-15).

Conclusion

9. Any inquiry concerning this communication or earlier communications from the examiner should be directed to SU C. KIM whose telephone number is (571)272-5972. The examiner can normally be reached on Monday - Friday, 10:00AM to 6:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew S. Smith can be reached on (571) 272-1907. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Su C Kim/ Examiner, Art Unit 2823

/W. David Coleman/

Primary Examiner, Art Unit 2823